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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/944,499

Filed: August 30, 2001

For: STABILIZERS FOR FLIP-CHIP TYPE

SEMICONDUCTOR DEVICES AND

SEMICONDUCTOR DEVICE

COMPONENTS AND ASSEMBLIES INCLUDING THE SAME (amended)

Examiner: A. Chambliss

Group Art Unit: 2827

Attorney Docket No.: 2269-3936.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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December 1, 2003

Date

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

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In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

U.S. Patent No.	Publication Date	<u>Patentee</u>
US 6,251,488	06/26/01	Miller et al.
US - 6,259,962	07/10/01	Gothait
US - 6,268,584	07/31/01	Keicher et al.
US - 6,326,698	12/04/01	Akram
US - 6,391,251	05/21/02	Keicher et al.
US - 6,461,881	10/08/02	Farnworth et al.
US - 6,506,671	01/14/03	Grigg
US - 6,525,408	02/25/03	Akram et al.
US - 6,544,821	04/08/03	Akram
US - 6,548,897	04/15/03	Grigg
US - 6,569,753	05/27/03	Akram et al.
US - 6,630,365	10/07/03	Farnworth et al.
US - 6,649,444	11/18/03	Earnworth et al.

Other Documents

- U.S. Patent Application Publication No. 2002/0105074 A1 to Akram et al., dated August 8, 2002
- U.S. Patent Application Publication No. 2002/0171177 A1 to Kritchman et al., dated November 21, 2002
- U.S. Patent Application Publication No. 2003/0022462 A1 to Farnworth et al., dated January 30, 2003
- U.S. Patent Application Publication No. 2003/0089999 A1 to Akram, dated May 15, 2003
- U.S. Patent Application Publication No. 2003/0092220 A1 to Akram, dated May 15, 2003

- U.S. Patent Application Publication No. 2003/0098499 A1 to Akram et al., dated May 29, 2003
- U.S. Patent Application Publication No. 2003/0139030 A1 to Grigg, dated July 24, 2003
- U.S. Patent Application Publication No. 2003/0151167 A1 to Kritchman et al., dated August 14, 2003
- U.S. Patent Application Publication No. 2003/0170921 A1 to Akram, dated September 11, 2003
- U.S. Patent Application Publication No. 2003/0173665 A1 to Grigg, dated September 18, 2003
- U.S. Patent Application Publication No. 2003/0176016 A1 to Grigg, dated September 18, 2003
- U.S. Patent Application Publication No. 2003/0203612 A1 to Akram et al., dated October 30, 2003
- MILLER et al., "Maskless Mesoscale Materials Deposition", Deposition Technology, September 2001, pages 20-22
- MILLER, "New Laser-Directed Deposition Technology", Microelectronic Fabrication, August 2001, page 16
- Webpage, Objet Prototyping the Future, Objet FullCure700 Series, 1 page
- Webpage, Objet Prototyping the Future, How it Works, 2 pages
- U.S. Patent Application No. 09/590, 527, filed June 8, 2000, entitled "Structures For Stabilizing Semiconductor Devices Relative to Test Substrates and Methods for Fabricating the Stabilizers", inventor Salman Akram
- U.S. Patent Application No. 10/201,208, filed July 22, 2002, entitled "Thick Solder Mask for Confining Encapsulant Material Over Selected Locations of a Substrate, Assemblies Including the Solder Mask, and Methods", inventor Grigg et al.
- U.S. Patent Application No. 10/688,354, filed October 17, 2003, entitled "Thick Solder Mask for Confining Encapsulant Material Over Selected Locations of a Substrate and Assemblies Including the Solder Mask", inventor Grigg et al.

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits.

The fee pursuant to 37 C.F.R. § 1.17(p) is enclosed.

Respectfully submitted,

Brick G. Power

Registration No. 38,581 Attorney for Applicant(s)

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Date: December 1, 2003

BGP/rmh

Enclosures: Form PTO-1449 or PTO/SB/08

Copy of documents cited Check No.5404 in the amount of \$180.00

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet

Complete if Known				
Application Number	09/944,499			
Filing Date	August 30, 2001			
First Named Inventor	Akram et al.			
Group Art Unit	2827			
Examiner Name	A. Chambliss			
Attorney Docket Number	3936.1US (99-0066.01/US)			

	Document Number		Name of Patentee or Applicant of	
Cite No.	Number - Kind Code ² (if known)	Publication Date MM-DD-YYYY	Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
	US- 6,251,488	06/26/01	Miller et al.	
	US- 6,259,962	07/10/01	Gothait	
	US- 6,268,584	07/31/01	Keicher et al.	
	US- 6,326,698	12/04/01	Akram	
	US- 6,391,251	05/21/02	Keicher et al.	
	US- 6,461,881	10/08/02	Farnworth et al.	
	US- 6,506,671	01/14/03	Grigg	
	US- 6,525,408	02/25/03	Akram et al.	
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	US- 6,548,897	04/15/03	Grigg	
	US- 6,569,753	05/27/03	Akram et al.	
	US- 6,630,365	10/07/03	Farnworth et al.	
	US- 6,649,444	11/18/03	Earnworth et al.	
	US-			

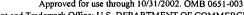
Examiner Cite	Foreign Patent Document		Name of Patentee or	Pages, Columns, Lines,		
Initials*	No.	Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)	Publication Date MM-DD-YYYY	i ippiiomii oi oilea	Where Relevant Passages or Relevant Figures Appear	T ⁶
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Examiner Signature	Date Considered	

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¹ Applicant's unique citation designation number (optional) . ² See Kinds Codes of USPTO Patent Documents at <u>www.uspto.gov</u> or MPEP 901.04. that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. Skind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.



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Substitute for form 1449A/PTO Complete if Known 09/944,499 Application Number INFORMATION DISCLOSURE Filing Date August 30, 2001 STATEMENT BY APPLICANT First Named Inventor Akram et al. 2827 Group Art Unit (use as many sheets as necessary) A. Chambliss **Examiner Name** 3936 LUS (99-0066 01/US) Attorney Docket Number

	OTHER PRIOR ART NON PATENT LITERATURE DOCUMENTS					
Examiner Initials *	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²			
		U.S. Patent Application Publication No. 2002/0105074 A1 to Akram et al., dated August 8, 2002				
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(use as many sheets as necessary) 3936 1US (99-0066 01/US)

Examiner Initials *	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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